

# CD4027B Types

## CMOS Dual J-K Master-Slave Flip-Flop

### High-Voltage Types (20-Volt Rating)

■ CD4027B is a single monolithic chip integrated circuit containing two identical complementary-symmetry J-K master-slave flip-flops. Each flip-flop has provisions for individual J, K, Set, Reset, and Clock input signals. Buffered Q and  $\bar{Q}$  signals are provided as outputs. This input-output arrangement provides for compatible operation with the RCA-CD4013B dual D-type flip-flop.

The CD4027B is useful in performing control, register, and toggle functions. Logic levels present at the J and K inputs along with internal self-steering control the state of each flip-flop; changes in the flip-flop state are synchronous with the positive-going transition of the clock pulse. Set and reset functions are independent of the clock and are initiated when a high level signal is present at either the Set or Reset input.

The CD4027B types are supplied in 16-lead hermetic dual-in-line ceramic packages (F3A suffix), 16-lead dual-in-line plastic packages (E suffix), 16-lead small-outline packages (M, M96, MT, and NSR suffixes), and 16-lead thin shrink small-outline packages (PW and PWR suffixes).

#### MAXIMUM RATINGS, Absolute-Maximum Values:

##### DC SUPPLY-VOLTAGE RANGE, ( $V_{DD}$ )

Voltages referenced to  $V_{SS}$  Terminal) ..... -0.5V to +20V

##### INPUT VOLTAGE RANGE, ALL INPUTS

..... -0.5V to  $V_{DD}$  + 0.5V

##### DC INPUT CURRENT, ANY ONE INPUT

.....  $\pm 10$ mA

##### POWER DISSIPATION PER PACKAGE ( $P_D$ ):

For  $T_A = -55^\circ\text{C}$  to  $+100^\circ\text{C}$  ..... 500mW

For  $T_A = +100^\circ\text{C}$  to  $+125^\circ\text{C}$  ..... Derate Linearly at 12mW/ $^\circ\text{C}$  to 200mW

##### DEVICE DISSIPATION PER OUTPUT TRANSISTOR

FOR  $T_A = \text{FULL PACKAGE-TEMPERATURE RANGE (All Package Types)}$  ..... 100mW

##### OPERATING-TEMPERATURE RANGE ( $T_A$ )

.....  $-55^\circ\text{C}$  to  $+125^\circ\text{C}$

##### STORAGE TEMPERATURE RANGE ( $T_{stg}$ )

.....  $-65^\circ\text{C}$  to  $+150^\circ\text{C}$

##### LEAD TEMPERATURE (DURING SOLDERING):

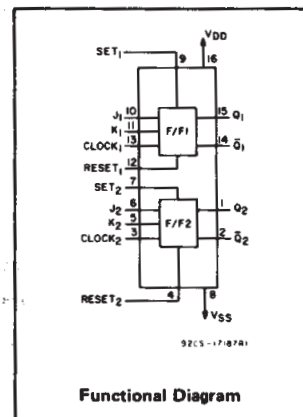
At distance  $1/16 \pm 1/32$  inch ( $1.59 \pm 0.79$ mm) from case for 10s max .....  $+265^\circ\text{C}$

#### Features:

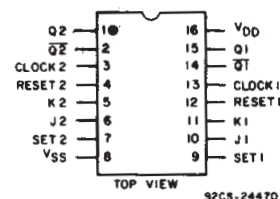
- Set-Reset capability
- Static flip-flop operation — retains state indefinitely with clock level either "high" or "low"
- Medium speed operation — 16 MHz (typ.) clock toggle rate at 10 V
- Standardized symmetrical output characteristics
- 100% tested for quiescent current at 20 V
- Maximum input current of  $1 \mu\text{A}$  at 18 V over full package-temperature range; 100 nA at 18 V and  $25^\circ\text{C}$
- Noise margin (over full package-temperature range):
  - 1 V at  $V_{DD} = 5 \text{ V}$
  - 2 V at  $V_{DD} = 10 \text{ V}$
  - 2.5 V at  $V_{DD} = 15 \text{ V}$
- 5-V, 10-V, and 15-V parametric ratings
- Meets all requirements of JEDEC Tentative Standard No. 13B, "Standard Specifications for Description of 'B' Series CMOS Devices"

#### Applications:

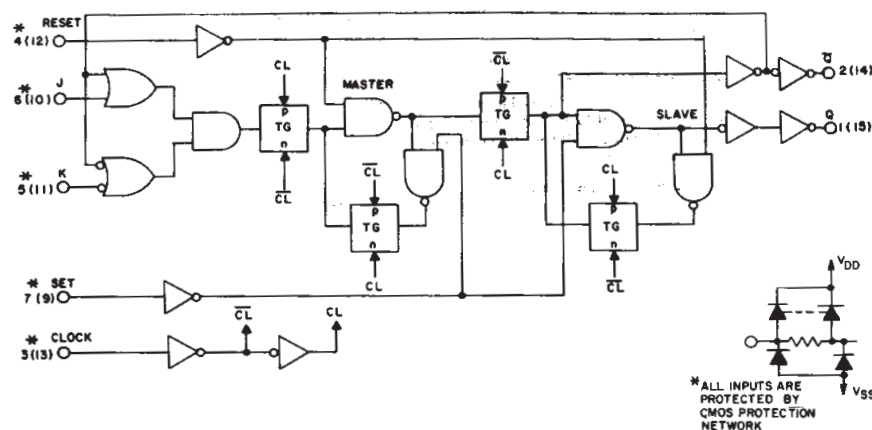
- Registers, counters, control circuits



Functional Diagram



TERMINAL ASSIGNMENT



| PRESENT STATE |   |   |   |   | NEXT STATE |           |
|---------------|---|---|---|---|------------|-----------|
| J             | K | S | R | Q | Q          | $\bar{Q}$ |
| 1             | x | 0 | 0 | 0 | 1          | 0         |
| x             | 0 | 0 | 0 | 1 | 1          | 0         |
| 0             | x | 0 | 0 | 0 | 0          | 1         |
| x             | 1 | 0 | 0 | 1 | 0          | 1         |
| x             | x | 0 | 0 | x | NO CHANGE  |           |
| x             | x | 1 | 0 | x | 1          | 0         |
| x             | x | 0 | 1 | x | 0          | 1         |
| x             | x | 1 | 1 | x | 1          | 1         |

LOGIC 1 = HIGH LEVEL  
LOGIC 0 = LOW LEVEL  
x = DON'T CARE

Fig. 1 — Logic diagram and truth table for CD4027B (one of two identical J-K flip flops).

## CD4027B Types

**RECOMMENDED OPERATING CONDITIONS** at  $T_A = 25^\circ\text{C}$ , Except as Noted.  
For maximum reliability, nominal operating conditions should be selected so that operation is always within the following ranges:

| CHARACTERISTIC                                                                | V <sub>DD</sub><br>(V) | LIMITS          |                | UNITS |
|-------------------------------------------------------------------------------|------------------------|-----------------|----------------|-------|
|                                                                               |                        | All Packages    |                |       |
|                                                                               |                        | Min.            | Max.           |       |
| Supply-Voltage Range<br>(For T <sub>A</sub> = Full Package Temperature Range) | —                      | 3               | 18             | V     |
| Data Setup Time<br>t <sub>S</sub>                                             | 5<br>10<br>15          | 200<br>75<br>50 | —<br>—<br>—    | ns    |
| Clock Pulse Width<br>t <sub>W</sub>                                           | 5<br>10<br>15          | 140<br>60<br>40 | —<br>—<br>—    | ns    |
| Clock Input Frequency (Toggle Mode)<br>f <sub>CL</sub>                        | 5<br>10<br>15          | dc              | 3.5<br>8<br>12 | MHz   |
| Clock Rise or Fall Time<br>t <sub>rCL</sub> *, t <sub>fCL</sub>               | 5<br>10<br>15          | —<br>—<br>—     | 45<br>5<br>2   | μs    |
| Set or Reset Pulse Width<br>t <sub>W</sub>                                    | 5<br>10<br>15          | 180<br>80<br>50 | —<br>—<br>—    | ns    |

\* If more than one unit is cascaded in a parallel clocked operation,  $t_{rCL}$  should be made less than or equal to the sum of the fixed propagation delay time at 15 pF and the transition time of the output driving stage for the estimated capacitive load.

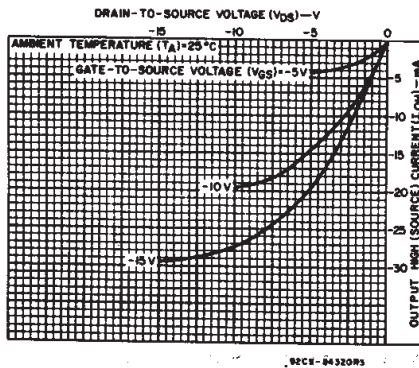


Fig. 4 - Typical output high (source) current characteristics.

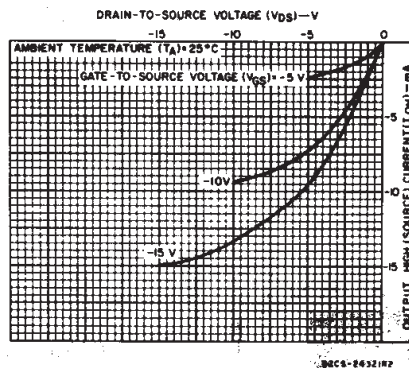


Fig. 5 - Minimum output high (source) current characteristics.

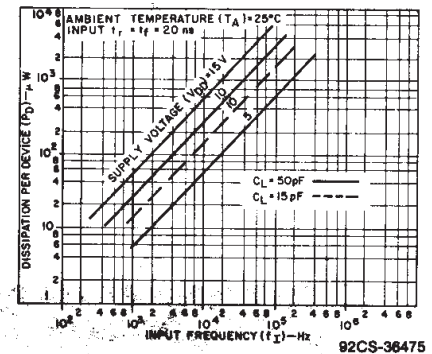


Fig. 6 - Typical power dissipation vs. frequency.

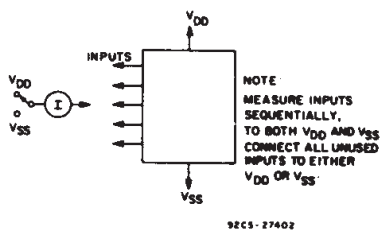


Fig. 7 - Input current test circuit.

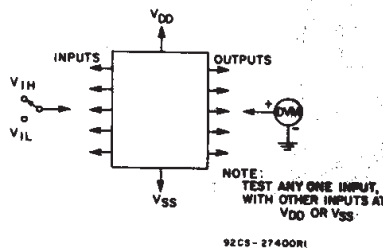


Fig. 8 - Input-voltage test circuit.

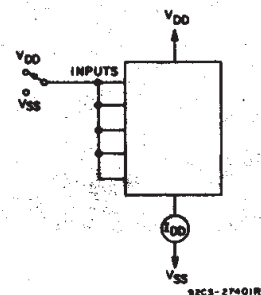
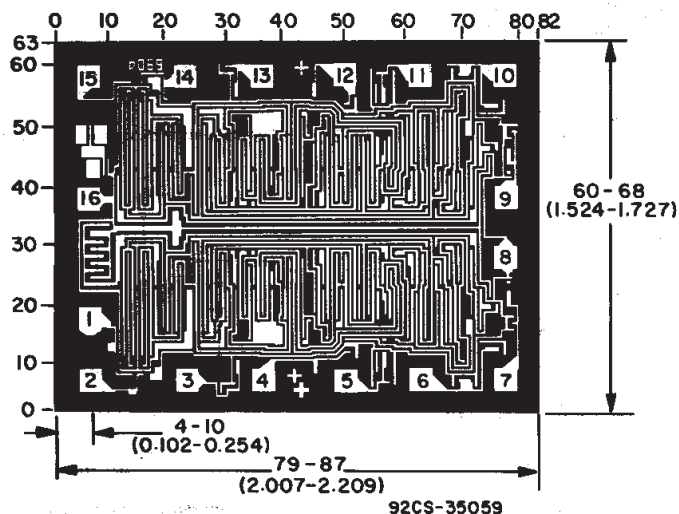


Fig. 9 - Quiescent device current test circuit.

# CD4027B Types

## STATIC ELECTRICAL CHARACTERISTICS

| CHARACTERISTIC                                     | CONDITIONS            |                        |                        | LIMITS AT INDICATED TEMPERATURES (°C) |       |       |       |       |                   |      | UNITS |
|----------------------------------------------------|-----------------------|------------------------|------------------------|---------------------------------------|-------|-------|-------|-------|-------------------|------|-------|
|                                                    | V <sub>O</sub><br>(V) | V <sub>IN</sub><br>(V) | V <sub>DD</sub><br>(V) | -55                                   | -40   | +85   | +125  | +25   |                   |      |       |
|                                                    |                       |                        |                        |                                       |       |       |       | Min.  | Typ.              | Max. |       |
| Quiescent Device Current, I <sub>DD</sub> Max.     | —                     | 0.5                    | 5                      | 1                                     | 1     | 30    | 30    | —     | 0.02              | 1    | μA    |
|                                                    | —                     | 0.10                   | 10                     | 2                                     | 2     | 60    | 60    | —     | 0.02              | 2    |       |
|                                                    | —                     | 0.15                   | 15                     | 4                                     | 4     | 120   | 120   | —     | 0.02              | 4    |       |
|                                                    | —                     | 0.20                   | 20                     | 20                                    | 20    | 600   | 600   | —     | 0.04              | 20   |       |
| Output Low (Sink) Current, I <sub>OL</sub> Min.    | 0.4                   | 0.5                    | 5                      | 0.64                                  | 0.61  | 0.42  | 0.36  | 0.51  | 1                 | —    | mA    |
|                                                    | 0.5                   | 0.10                   | 10                     | 1.6                                   | 1.5   | 1.1   | 0.9   | 1.3   | 2.6               | —    |       |
|                                                    | 1.5                   | 0.15                   | 15                     | 4.2                                   | 4     | 2.8   | 2.4   | 3.4   | 6.8               | —    |       |
|                                                    | 4.6                   | 0.5                    | 5                      | -0.64                                 | -0.61 | -0.42 | -0.36 | -0.51 | -1                | —    |       |
|                                                    | 2.5                   | 0.5                    | 5                      | -2                                    | -1.8  | -1.3  | -1.15 | -1.6  | -3.2              | —    |       |
|                                                    | 9.5                   | 0.10                   | 10                     | -1.6                                  | -1.5  | -1.1  | -0.9  | -1.3  | -2.6              | —    |       |
| Output High (Source) Current, I <sub>OH</sub> Min. | 13.5                  | 0.15                   | 15                     | -4.2                                  | -4    | -2.8  | -2.4  | -3.4  | -6.8              | —    |       |
|                                                    |                       |                        |                        |                                       |       |       |       |       |                   |      |       |
|                                                    |                       |                        |                        |                                       |       |       |       |       |                   |      |       |
|                                                    |                       |                        |                        |                                       |       |       |       |       |                   |      |       |
| Output Voltage: Low-Level, V <sub>OL</sub> Max.    | —                     | 0.5                    | 5                      | 0.05                                  |       |       |       | —     | 0                 | 0.05 | V     |
|                                                    | —                     | 0.10                   | 10                     | 0.05                                  |       |       |       | —     | 0                 | 0.05 |       |
|                                                    | —                     | 0.15                   | 15                     | 0.05                                  |       |       |       | —     | 0                 | 0.05 |       |
| Output Voltage: High-Level, V <sub>OH</sub> Min.   | —                     | 0.5                    | 5                      | 4.95                                  |       |       |       | 4.95  | 5                 | —    |       |
|                                                    | —                     | 0.10                   | 10                     | 9.95                                  |       |       |       | 9.95  | 10                | —    |       |
|                                                    | —                     | 0.15                   | 15                     | 14.95                                 |       |       |       | 14.95 | 15                | —    |       |
| Input Low Voltage, V <sub>IL</sub> Max.            | 0.5,4.5               | —                      | 5                      | 1.5                                   |       |       |       | —     | —                 | 1.5  | V     |
|                                                    | 1.9                   | —                      | 10                     | 3                                     |       |       |       | —     | —                 | 3    |       |
|                                                    | 1.5,13.5              | —                      | 15                     | 4                                     |       |       |       | —     | —                 | 4    |       |
| Input High Voltage, V <sub>IH</sub> Min.           | 0.5,4.5               | —                      | 5                      | 3.5                                   |       |       |       | 3.5   | —                 | —    |       |
|                                                    | 1.9                   | —                      | 10                     | 7                                     |       |       |       | 7     | —                 | —    |       |
|                                                    | 1.5,13.5              | —                      | 15                     | 11                                    |       |       |       | 11    | —                 | —    |       |
| Input Current, I <sub>IN</sub> Max.                | —                     | 0.18                   | 18                     | ±0.1                                  | ±0.1  | ±1    | ±1    | —     | ±10 <sup>-5</sup> | ±0.1 | μA    |



the 1990s, the number of people in the world who are under 15 years of age is expected to increase from 1.1 billion to 1.5 billion. The number of people aged 65 and over is expected to increase from 250 million to 450 million. The number of people aged 15 and over is expected to increase from 3.5 billion to 4.5 billion. The number of people aged 15 and over is expected to increase from 3.5 billion to 4.5 billion. The number of people aged 15 and over is expected to increase from 3.5 billion to 4.5 billion.

**DYNAMIC ELECTRICAL CHARACTERISTICS** at  $T_A = 25^{\circ}\text{C}$ ; Input  $t_r, t_f = 20 \text{ ns}$ ,  
 $C_L = 50 \text{ pF}$ ,  $R_L = 200 \text{ k}\Omega$

| CHARACTERISTIC                                                                   | V <sub>DD</sub><br>(V) | LIMITS         |                 |                   | UNITS   |
|----------------------------------------------------------------------------------|------------------------|----------------|-----------------|-------------------|---------|
|                                                                                  |                        | All Packages   |                 |                   |         |
|                                                                                  |                        | Min.           | Typ.            | Max.              |         |
| Propagation Delay Time:<br>Clock to Q or $\bar{Q}$ Outputs<br>$t_{PHL}, t_{PLH}$ | 5<br>10<br>15          | —<br>—<br>—    | 150<br>65<br>45 | 300<br>130<br>90  | ns      |
| Set to Q or Reset to $\bar{Q}$ $t_{PLH}$                                         | 5<br>10<br>15          | —<br>—<br>—    | 150<br>65<br>45 | 300<br>130<br>90  | ns      |
| Set to $\bar{Q}$ or Reset to Q $t_{PHL}$                                         | 5<br>10<br>15          | —<br>—<br>—    | 200<br>85<br>60 | 400<br>170<br>120 | ns      |
| Transition Time $t_{THL}, t_{TLH}$                                               | 5<br>10<br>15          | —<br>—<br>—    | 100<br>50<br>40 | 200<br>100<br>80  | ns      |
| Maximum Clock Input<br>Frequency# (Toggle Mode)<br>$f_{CL}$                      | 5<br>10<br>15          | 3.5<br>8<br>12 | 7<br>16<br>24   | —<br>—<br>—       | MHz     |
| Minimum Clock Pulse Width $t_W$                                                  | 5<br>10<br>15          | —<br>—<br>—    | 70<br>30<br>20  | 140<br>60<br>40   | ns      |
| Minimum Set or Reset Pulse<br>Width $t_W$                                        | 5<br>10<br>15          | —<br>—<br>—    | 90<br>40<br>25  | 180<br>80<br>50   | ns      |
| Minimum Data Setup Time $t_S$                                                    | 5<br>10<br>15          | —<br>—<br>—    | 100<br>35<br>25 | 200<br>75<br>50   | ns      |
| Clock Input Rise or Fall Time<br>$t_{rCL}, t_{fCL}$                              | 5<br>10<br>15          | —<br>—<br>—    | —<br>—<br>—     | 45<br>5<br>2      | $\mu$ s |
| Input Capacitance $C_i$                                                          |                        | —              | 5               | 7.5               | pF      |

# Input  $t_r, t_f = 5 \text{ ns}$ .

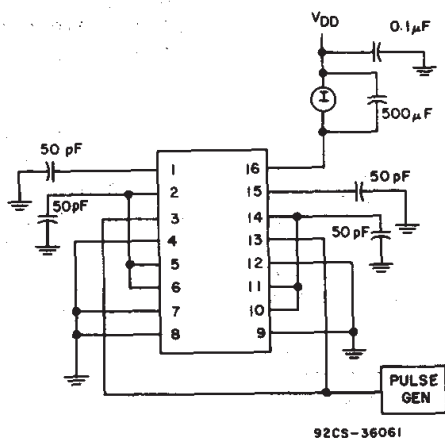
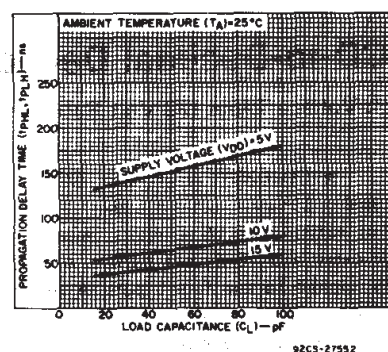
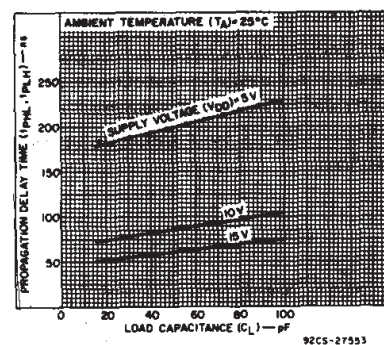


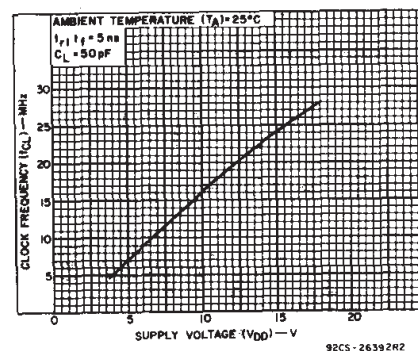
Fig. 13—Dynamic power dissipation test circuit.



**Fig. 10 – Typical propagation delay time vs. load capacitance (CLOCK or SET to Q, CLOCK or RESET to  $\bar{Q}$ ).**



**Fig.11— Typical propagation delay time vs. load capacitance (SET to  $\bar{Q}$  or RESET to Q).**



**Fig.12— Typical maximum clock frequency vs. supply voltage (toggle mode).**

**PACKAGING INFORMATION**

| Orderable Device | Status <sup>(1)</sup> | Package Type | Package Drawing | Pins | Package Qty | Eco Plan <sup>(2)</sup> | Lead/Ball Finish | MSL Peak Temp <sup>(3)</sup> |
|------------------|-----------------------|--------------|-----------------|------|-------------|-------------------------|------------------|------------------------------|
| CD4027BE         | ACTIVE                | PDIP         | N               | 16   | 25          | Pb-Free (RoHS)          | CU NIPDAU        | N / A for Pkg Type           |
| CD4027BEE4       | ACTIVE                | PDIP         | N               | 16   | 25          | Pb-Free (RoHS)          | CU NIPDAU        | N / A for Pkg Type           |
| CD4027BF         | ACTIVE                | CDIP         | J               | 16   | 1           | TBD                     | A42              | N / A for Pkg Type           |
| CD4027BF3A       | ACTIVE                | CDIP         | J               | 16   | 1           | TBD                     | A42              | N / A for Pkg Type           |
| CD4027BF3AS2534  | OBSOLETE              | CDIP         | J               | 16   |             | TBD                     | Call TI          | Call TI                      |
| CD4027BM         | ACTIVE                | SOIC         | D               | 16   | 40          | Green (RoHS & no Sb/Br) | CU NIPDAU        | Level-1-260C-UNLIM           |
| CD4027BM96       | ACTIVE                | SOIC         | D               | 16   | 2500        | Green (RoHS & no Sb/Br) | CU NIPDAU        | Level-1-260C-UNLIM           |
| CD4027BM96E4     | ACTIVE                | SOIC         | D               | 16   | 2500        | Green (RoHS & no Sb/Br) | CU NIPDAU        | Level-1-260C-UNLIM           |
| CD4027BM96G4     | ACTIVE                | SOIC         | D               | 16   | 2500        | Green (RoHS & no Sb/Br) | CU NIPDAU        | Level-1-260C-UNLIM           |
| CD4027BME4       | ACTIVE                | SOIC         | D               | 16   | 40          | Green (RoHS & no Sb/Br) | CU NIPDAU        | Level-1-260C-UNLIM           |
| CD4027BMG4       | ACTIVE                | SOIC         | D               | 16   | 40          | Green (RoHS & no Sb/Br) | CU NIPDAU        | Level-1-260C-UNLIM           |
| CD4027BMT        | ACTIVE                | SOIC         | D               | 16   | 250         | Green (RoHS & no Sb/Br) | CU NIPDAU        | Level-1-260C-UNLIM           |
| CD4027BMTE4      | ACTIVE                | SOIC         | D               | 16   | 250         | Green (RoHS & no Sb/Br) | CU NIPDAU        | Level-1-260C-UNLIM           |
| CD4027BMTG4      | ACTIVE                | SOIC         | D               | 16   | 250         | Green (RoHS & no Sb/Br) | CU NIPDAU        | Level-1-260C-UNLIM           |
| CD4027BNSR       | ACTIVE                | SO           | NS              | 16   | 2000        | Green (RoHS & no Sb/Br) | CU NIPDAU        | Level-1-260C-UNLIM           |
| CD4027BNSRE4     | ACTIVE                | SO           | NS              | 16   | 2000        | Green (RoHS & no Sb/Br) | CU NIPDAU        | Level-1-260C-UNLIM           |
| CD4027BNSRG4     | ACTIVE                | SO           | NS              | 16   | 2000        | Green (RoHS & no Sb/Br) | CU NIPDAU        | Level-1-260C-UNLIM           |
| CD4027BPW        | ACTIVE                | TSSOP        | PW              | 16   | 90          | Green (RoHS & no Sb/Br) | CU NIPDAU        | Level-1-260C-UNLIM           |
| CD4027BPWE4      | ACTIVE                | TSSOP        | PW              | 16   | 90          | Green (RoHS & no Sb/Br) | CU NIPDAU        | Level-1-260C-UNLIM           |
| CD4027BPWG4      | ACTIVE                | TSSOP        | PW              | 16   | 90          | Green (RoHS & no Sb/Br) | CU NIPDAU        | Level-1-260C-UNLIM           |
| CD4027BPWR       | ACTIVE                | TSSOP        | PW              | 16   | 2000        | Green (RoHS & no Sb/Br) | CU NIPDAU        | Level-1-260C-UNLIM           |
| CD4027BPWRE4     | ACTIVE                | TSSOP        | PW              | 16   | 2000        | Green (RoHS & no Sb/Br) | CU NIPDAU        | Level-1-260C-UNLIM           |
| CD4027BPWRG4     | ACTIVE                | TSSOP        | PW              | 16   | 2000        | Green (RoHS & no Sb/Br) | CU NIPDAU        | Level-1-260C-UNLIM           |
| JM38510/05152BEA | ACTIVE                | CDIP         | J               | 16   | 1           | TBD                     | A42              | N / A for Pkg Type           |

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.



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**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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**TAPE AND REEL INFORMATION**



\*All dimensions are nominal

| Device     | Package Type | Package Drawing | Pins | SPQ  | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|------------|--------------|-----------------|------|------|--------------------|--------------------|---------|---------|---------|---------|--------|---------------|
| CD4027BM96 | SOIC         | D               | 16   | 2500 | 330.0              | 16.4               | 6.5     | 10.3    | 2.1     | 8.0     | 16.0   | Q1            |
| CD4027BNSR | SO           | NS              | 16   | 2000 | 330.0              | 16.4               | 8.2     | 10.5    | 2.5     | 12.0    | 16.0   | Q1            |
| CD4027BPWR | TSSOP        | PW              | 16   | 2000 | 330.0              | 12.4               | 7.0     | 5.6     | 1.6     | 8.0     | 12.0   | Q1            |

## TAPE AND REEL BOX DIMENSIONS



\*All dimensions are nominal

| Device     | Package Type | Package Drawing | Pins | SPQ  | Length (mm) | Width (mm) | Height (mm) |
|------------|--------------|-----------------|------|------|-------------|------------|-------------|
| CD4027BM96 | SOIC         | D               | 16   | 2500 | 333.2       | 345.9      | 28.6        |
| CD4027BNSR | SO           | NS              | 16   | 2000 | 346.0       | 346.0      | 33.0        |
| CD4027BPWR | TSSOP        | PW              | 16   | 2000 | 346.0       | 346.0      | 29.0        |



## PW (R-PDSO-G\*\*)

## PLASTIC SMALL-OUTLINE PACKAGE

14 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.  
 D. Falls within JEDEC MO-153

# MECHANICAL DATA

NS (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



| DIM \ PINS ** | 14    | 16    | 20    | 24    |
|---------------|-------|-------|-------|-------|
| A MAX         | 10,50 | 10,50 | 12,90 | 15,30 |
| A MIN         | 9,90  | 9,90  | 12,30 | 14,70 |

4040062/C 03/03

- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

J (R-GDIP-T\*\*)

14 LEADS SHOWN

# CERAMIC DUAL IN-LINE PACKAGE



| PINS **<br>DIM | 14                     | 16                     | 18                     | 20                     |
|----------------|------------------------|------------------------|------------------------|------------------------|
| A              | 0.300<br>(7,62)<br>BSC | 0.300<br>(7,62)<br>BSC | 0.300<br>(7,62)<br>BSC | 0.300<br>(7,62)<br>BSC |
| B MAX          | 0.785<br>(19,94)       | .840<br>(21,34)        | 0.960<br>(24,38)       | 1.060<br>(26,92)       |
| B MIN          | —                      | —                      | —                      | —                      |
| C MAX          | 0.300<br>(7,62)        | 0.300<br>(7,62)        | 0.310<br>(7,87)        | 0.300<br>(7,62)        |
| C MIN          | 0.245<br>(6,22)        | 0.245<br>(6,22)        | 0.220<br>(5,59)        | 0.245<br>(6,22)        |

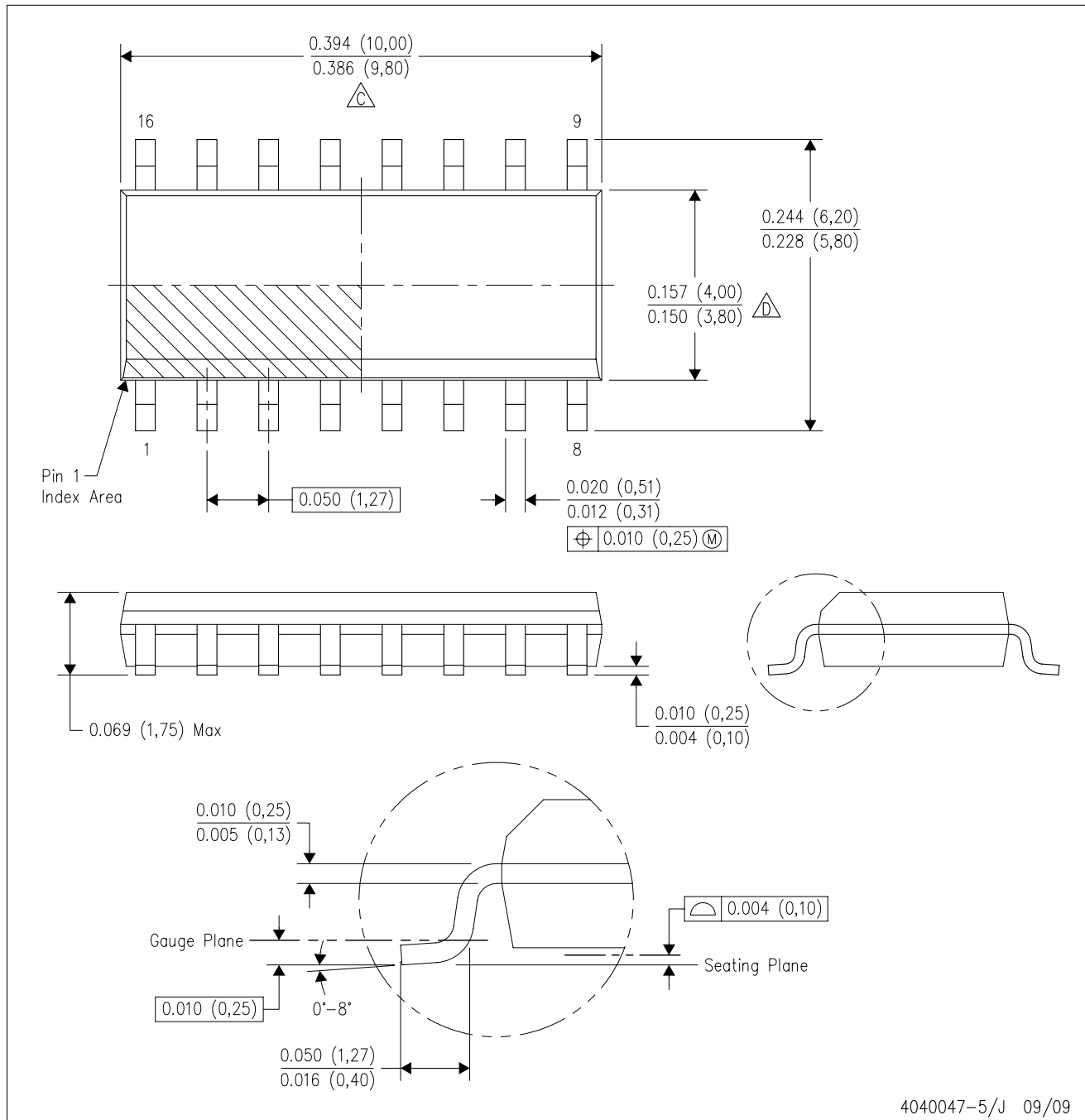


4040083/F 03/03

- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. This package is hermetically sealed with a ceramic lid using glass frit.
  - D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
  - E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

D (R-PDSO-G16)

PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - $\triangle C$  Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
  - $\triangle D$  Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
  - E. Reference JEDEC MS-012 variation AC.

## D(R-PDSO-G16)



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Refer to IPC7351 for alternate board design.
  - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525
  - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

N (R-PDIP-T\*\*)

16 PINS SHOWN

## PLASTIC DUAL-IN-LINE PACKAGE



| PINS **<br>DIM      | 14               | 16               | 18               | 20               |
|---------------------|------------------|------------------|------------------|------------------|
| A MAX               | 0.775<br>(19,69) | 0.775<br>(19,69) | 0.920<br>(23,37) | 1.060<br>(26,92) |
| A MIN               | 0.745<br>(18,92) | 0.745<br>(18,92) | 0.850<br>(21,59) | 0.940<br>(23,88) |
| MS-001<br>VARIATION | AA               | BB               | AC               | AD               |



4040049/E 12/2002

- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  -  Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
  -  The 20 pin end lead shoulder width is a vendor option, either half or full width.



**PACKAGING INFORMATION**

| Orderable Device | Status<br>(1) | Package Type | Package<br>Drawing | Pins | Package<br>Qty | Eco Plan<br>(2)            | Lead/Ball Finish<br>(6) | MSL Peak Temp<br>(3) | Op Temp (°C) | Device Marking<br>(4/5) | Samples                 |
|------------------|---------------|--------------|--------------------|------|----------------|----------------------------|-------------------------|----------------------|--------------|-------------------------|-------------------------|
| CD4027BE         | ACTIVE        | PDIP         | N                  | 16   | 25             | Pb-Free<br>(RoHS)          | CU NIPDAU               | N / A for Pkg Type   | -55 to 125   | CD4027BE                | <a href="#">Samples</a> |
| CD4027BEE4       | ACTIVE        | PDIP         | N                  | 16   | 25             | Pb-Free<br>(RoHS)          | CU NIPDAU               | N / A for Pkg Type   | -55 to 125   | CD4027BE                | <a href="#">Samples</a> |
| CD4027BF         | ACTIVE        | CDIP         | J                  | 16   | 1              | TBD                        | A42                     | N / A for Pkg Type   | -55 to 125   | CD4027BF                | <a href="#">Samples</a> |
| CD4027BF3A       | ACTIVE        | CDIP         | J                  | 16   | 1              | TBD                        | A42                     | N / A for Pkg Type   | -55 to 125   | CD4027BF3A              | <a href="#">Samples</a> |
| CD4027BF3AS2534  | OBSOLETE      | CDIP         | J                  | 16   |                | TBD                        | Call TI                 | Call TI              |              |                         |                         |
| CD4027BM         | ACTIVE        | SOIC         | D                  | 16   | 40             | Green (RoHS<br>& no Sb/Br) | CU NIPDAU               | Level-1-260C-UNLIM   | -55 to 125   | CD4027BM                | <a href="#">Samples</a> |
| CD4027BM96       | ACTIVE        | SOIC         | D                  | 16   | 2500           | Green (RoHS<br>& no Sb/Br) | CU NIPDAU               | Level-1-260C-UNLIM   | -55 to 125   | CD4027BM                | <a href="#">Samples</a> |
| CD4027BM96E4     | ACTIVE        | SOIC         | D                  | 16   | 2500           | Green (RoHS<br>& no Sb/Br) | CU NIPDAU               | Level-1-260C-UNLIM   | -55 to 125   | CD4027BM                | <a href="#">Samples</a> |
| CD4027BME4       | ACTIVE        | SOIC         | D                  | 16   | 40             | Green (RoHS<br>& no Sb/Br) | CU NIPDAU               | Level-1-260C-UNLIM   | -55 to 125   | CD4027BM                | <a href="#">Samples</a> |
| CD4027BMG4       | ACTIVE        | SOIC         | D                  | 16   | 40             | Green (RoHS<br>& no Sb/Br) | CU NIPDAU               | Level-1-260C-UNLIM   | -55 to 125   | CD4027BM                | <a href="#">Samples</a> |
| CD4027BMT        | ACTIVE        | SOIC         | D                  | 16   | 250            | Green (RoHS<br>& no Sb/Br) | CU NIPDAU               | Level-1-260C-UNLIM   | -55 to 125   | CD4027BM                | <a href="#">Samples</a> |
| CD4027BNSR       | ACTIVE        | SO           | NS                 | 16   | 2000           | Green (RoHS<br>& no Sb/Br) | CU NIPDAU               | Level-1-260C-UNLIM   | -55 to 125   | CD4027B                 | <a href="#">Samples</a> |
| CD4027BNSRE4     | ACTIVE        | SO           | NS                 | 16   | 2000           | Green (RoHS<br>& no Sb/Br) | CU NIPDAU               | Level-1-260C-UNLIM   | -55 to 125   | CD4027B                 | <a href="#">Samples</a> |
| CD4027BNSRG4     | ACTIVE        | SO           | NS                 | 16   | 2000           | Green (RoHS<br>& no Sb/Br) | CU NIPDAU               | Level-1-260C-UNLIM   | -55 to 125   | CD4027B                 | <a href="#">Samples</a> |
| CD4027BPW        | ACTIVE        | TSSOP        | PW                 | 16   | 90             | Green (RoHS<br>& no Sb/Br) | CU NIPDAU               | Level-1-260C-UNLIM   | -55 to 125   | CM027B                  | <a href="#">Samples</a> |
| CD4027BPWR       | ACTIVE        | TSSOP        | PW                 | 16   | 2000           | Green (RoHS<br>& no Sb/Br) | CU NIPDAU               | Level-1-260C-UNLIM   | -55 to 125   | CM027B                  | <a href="#">Samples</a> |
| CD4027BPWRG4     | ACTIVE        | TSSOP        | PW                 | 16   | 2000           | Green (RoHS<br>& no Sb/Br) | CU NIPDAU               | Level-1-260C-UNLIM   | -55 to 125   | CM027B                  | <a href="#">Samples</a> |
| JM38510/05152BEA | ACTIVE        | CDIP         | J                  | 16   | 1              | TBD                        | A42                     | N / A for Pkg Type   | -55 to 125   | JM38510/<br>05152BEA    | <a href="#">Samples</a> |

| Orderable Device | Status<br>(1) | Package Type | Package<br>Drawing | Pins | Package<br>Qty | Eco Plan<br>(2) | Lead/Ball Finish<br>(6) | MSL Peak Temp<br>(3) | Op Temp (°C) | Device Marking<br>(4/5) | Samples                 |
|------------------|---------------|--------------|--------------------|------|----------------|-----------------|-------------------------|----------------------|--------------|-------------------------|-------------------------|
| M38510/05152BEA  | ACTIVE        | CDIP         | J                  | 16   | 1              | TBD             | A42                     | N / A for Pkg Type   | -55 to 125   | JM38510/<br>05152BEA    | <a href="#">Samples</a> |

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSELETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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**OTHER QUALIFIED VERSIONS OF CD4027B, CD4027B-MIL :**

- Catalog: [CD4027B](#)
- Military: [CD4027B-MIL](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Military - QML certified for Military and Defense Applications

**TAPE AND REEL INFORMATION**
**REEL DIMENSIONS**

**TAPE DIMENSIONS**


|    |                                                           |
|----|-----------------------------------------------------------|
| A0 | Dimension designed to accommodate the component width     |
| B0 | Dimension designed to accommodate the component length    |
| K0 | Dimension designed to accommodate the component thickness |
| W  | Overall width of the carrier tape                         |
| P1 | Pitch between successive cavity centers                   |

**TAPE AND REEL INFORMATION**

\*All dimensions are nominal

| Device     | Package Type | Package Drawing | Pins | SPQ  | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|------------|--------------|-----------------|------|------|--------------------|--------------------|---------|---------|---------|---------|--------|---------------|
| CD4027BM96 | SOIC         | D               | 16   | 2500 | 330.0              | 16.4               | 6.5     | 10.3    | 2.1     | 8.0     | 16.0   | Q1            |
| CD4027BNSR | SO           | NS              | 16   | 2000 | 330.0              | 16.4               | 8.2     | 10.5    | 2.5     | 12.0    | 16.0   | Q1            |
| CD4027BPWR | TSSOP        | PW              | 16   | 2000 | 330.0              | 12.4               | 6.9     | 5.6     | 1.6     | 8.0     | 12.0   | Q1            |

## TAPE AND REEL BOX DIMENSIONS



\*All dimensions are nominal

| Device     | Package Type | Package Drawing | Pins | SPQ  | Length (mm) | Width (mm) | Height (mm) |
|------------|--------------|-----------------|------|------|-------------|------------|-------------|
| CD4027BM96 | SOIC         | D               | 16   | 2500 | 333.2       | 345.9      | 28.6        |
| CD4027BNSR | SO           | NS              | 16   | 2000 | 367.0       | 367.0      | 38.0        |
| CD4027BPWR | TSSOP        | PW              | 16   | 2000 | 367.0       | 367.0      | 35.0        |

J (R-GDIP-T\*\*)

14 LEADS SHOWN

# CERAMIC DUAL IN-LINE PACKAGE



| PINS **<br>DIM | 14                     | 16                     | 18                     | 20                     |
|----------------|------------------------|------------------------|------------------------|------------------------|
| A              | 0.300<br>(7,62)<br>BSC | 0.300<br>(7,62)<br>BSC | 0.300<br>(7,62)<br>BSC | 0.300<br>(7,62)<br>BSC |
| B MAX          | 0.785<br>(19,94)       | .840<br>(21,34)        | 0.960<br>(24,38)       | 1.060<br>(26,92)       |
| B MIN          | —                      | —                      | —                      | —                      |
| C MAX          | 0.300<br>(7,62)        | 0.300<br>(7,62)        | 0.310<br>(7,87)        | 0.300<br>(7,62)        |
| C MIN          | 0.245<br>(6,22)        | 0.245<br>(6,22)        | 0.220<br>(5,59)        | 0.245<br>(6,22)        |



4040083/F 03/03

- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. This package is hermetically sealed with a ceramic lid using glass frit.
  - D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
  - E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.



N (R-PDIP-T\*\*)

16 PINS SHOWN

## PLASTIC DUAL-IN-LINE PACKAGE



| PINS **<br>DIM      | 14               | 16               | 18               | 20               |
|---------------------|------------------|------------------|------------------|------------------|
| A MAX               | 0.775<br>(19,69) | 0.775<br>(19,69) | 0.920<br>(23,37) | 1.060<br>(26,92) |
| A MIN               | 0.745<br>(18,92) | 0.745<br>(18,92) | 0.850<br>(21,59) | 0.940<br>(23,88) |
| MS-001<br>VARIATION | AA               | BB               | AC               | AD               |



4040049/E 12/2002

NOTES:

- A. All linear dimensions are in inches (millimeters).  
B. This drawing is subject to change without notice.
-  Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).  
 The 20 pin end lead shoulder width is a vendor option, either half or full width.

D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - $\triangle C$  Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
  - $\triangle D$  Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
  - E. Reference JEDEC MS-012 variation AC.

D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



- NOTES:
- All linear dimensions are in millimeters.
  - This drawing is subject to change without notice.
  - Publication IPC-7351 is recommended for alternate designs.
  - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
  - Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

PW (R-PDSO-G16)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
  - B. This drawing is subject to change without notice.
  - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
  - D. Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
  - E. Falls within JEDEC MO-153

PW (R-PDSO-G16)

PLASTIC SMALL OUTLINE



4211284-3/F 12/12

- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Publication IPC-7351 is recommended for alternate designs.
  - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
  - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

# MECHANICAL DATA

NS (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



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| Data Converters              | <a href="http://dataconverter.ti.com">dataconverter.ti.com</a>                       |
| DLP® Products                | <a href="http://www.dlp.com">www.dlp.com</a>                                         |
| DSP                          | <a href="http://dsp.ti.com">dsp.ti.com</a>                                           |
| Clocks and Timers            | <a href="http://www.ti.com/clocks">www.ti.com/clocks</a>                             |
| Interface                    | <a href="http://interface.ti.com">interface.ti.com</a>                               |
| Logic                        | <a href="http://logic.ti.com">logic.ti.com</a>                                       |
| Power Mgmt                   | <a href="http://power.ti.com">power.ti.com</a>                                       |
| Microcontrollers             | <a href="http://microcontroller.ti.com">microcontroller.ti.com</a>                   |
| RFID                         | <a href="http://www.ti-rfid.com">www.ti-rfid.com</a>                                 |
| OMAP Applications Processors | <a href="http://www.ti.com/omap">www.ti.com/omap</a>                                 |
| Wireless Connectivity        | <a href="http://www.ti.com/wirelessconnectivity">www.ti.com/wirelessconnectivity</a> |

### Applications

|                               |                                                                                          |
|-------------------------------|------------------------------------------------------------------------------------------|
| Automotive and Transportation | <a href="http://www.ti.com/automotive">www.ti.com/automotive</a>                         |
| Communications and Telecom    | <a href="http://www.ti.com/communications">www.ti.com/communications</a>                 |
| Computers and Peripherals     | <a href="http://www.ti.com/computers">www.ti.com/computers</a>                           |
| Consumer Electronics          | <a href="http://www.ti.com/consumer-apps">www.ti.com/consumer-apps</a>                   |
| Energy and Lighting           | <a href="http://www.ti.com/energy">www.ti.com/energy</a>                                 |
| Industrial                    | <a href="http://www.ti.com/industrial">www.ti.com/industrial</a>                         |
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